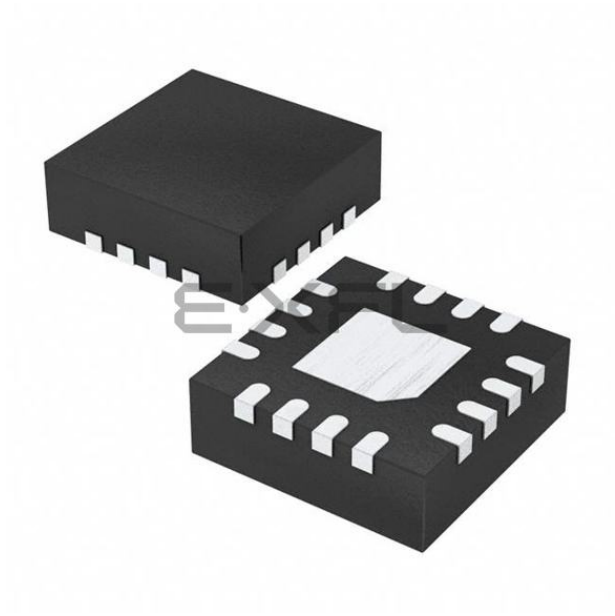


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-VQFN Exposed Pad
Supplier Device Package	16-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f684-i-ml

Table of Contents

TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at **docerrors@microchip.com** or fax the **Reader Response Form** in the back of this data sheet to (480) 792-4150. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

http://www.microchip.com

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000A is version A of document DS30000).

Errata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

- Microchip's Worldwide Web site; http://www.microchip.com
- Your local Microchip sales office (see last page)

When contacting a sales office, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at **www.microchip.com** to receive the most current information on all of our products.

2.2.2.6 PCON Register

The Power Control (PCON) register (see Table 12-2) contains flag bits to differentiate between a:

- Power-on Reset ($\overline{POR}$)
- Brown-out Reset ($\overline{BOR}$)
- Watchdog Timer Reset (WDT)
- External $\overline{MCLR}$ Reset

The PCON register also controls the Ultra Low-Power Wake-up and software enable of the $\overline{BOR}$.

The PCON register bits are shown in Register 2-6.

REGISTER 2-6: PCON: POWER CONTROL REGISTER

U-0	U-0	R/W-0	R/W-1	U-0	U-0	R/W-0	R/W-x
—	—	ULPWUE	SBOREN	—	—	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5 **ULPWUE:** Ultra Low-Power Wake-Up Enable bit
1 = Ultra Low-Power Wake-up enabled
0 = Ultra Low-Power Wake-up disabled

bit 4 **SBOREN:** Software BOR Enable bit(1)
1 = BOR enabled
0 = BOR disabled

bit 3-2 **Unimplemented:** Read as '0'

bit 1 **$\overline{POR}$:** Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{BOR}$:** Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Power-on Reset or Brown-out Reset occurs)

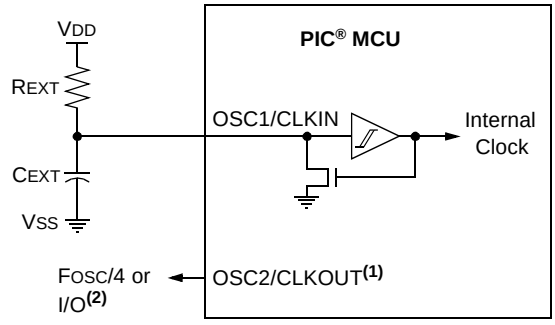
Note 1: BOREN<1:0> = 01 in the Configuration Word register for this bit to control the $\overline{BOR}$.

3.4.4 EXTERNAL RC MODES

The external Resistor-Capacitor (RC) modes support the use of an external RC circuit. This allows the designer maximum flexibility in frequency choice while keeping costs to a minimum when clock accuracy is not required. There are two modes: RC and RCIO.

In RC mode, the RC circuit connects to OSC1. OSC2/CLKOUT outputs the RC oscillator frequency divided by 4. This signal may be used to provide a clock for external circuitry, synchronization, calibration, test or other application requirements. Figure 3-5 shows the external RC mode connections.

FIGURE 3-5: EXTERNAL RC MODES



Recommended values: 10 kΩ ≤ REXT ≤ 100 kΩ, <3V
3 kΩ ≤ REXT ≤ 100 kΩ, 3-5V
CEXT > 20 pF, 2-5V

Note 1: Alternate pin functions are listed in **Section 1.0 "Device Overview"**.

2: Output depends upon RC or RCIO Clock mode.

In RCIO mode, the RC circuit is connected to OSC1. OSC2 becomes an additional general purpose I/O pin.

The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values and the operating temperature. Other factors affecting the oscillator frequency are:

- threshold voltage variation
- component tolerances
- packaging variations in capacitance

The user also needs to take into account variation due to tolerance of external RC components used.

3.5 Internal Clock Modes

The Oscillator module has two independent, internal oscillators that can be configured or selected as the system clock source.

1. The **HFINTOSC** (High-Frequency Internal Oscillator) is factory calibrated and operates at 8 MHz. The frequency of the HFINTOSC can be user-adjusted via software using the OSCTUNE register (Register 3-2).
2. The **LFINTOSC** (Low-Frequency Internal Oscillator) is uncalibrated and operates at 31 kHz.

The system clock speed can be selected via software using the Internal Oscillator Frequency Select bits IRCF<2:0> of the OSCCON register.

The system clock can be selected between external or internal clock sources via the System Clock Selection (SCS) bit of the OSCCON register. See **Section 3.6 "Clock Switching"** for more information.

3.5.1 INTOSC AND INTOSCIO MODES

The INTOSC and INTOSCIO modes configure the internal oscillators as the system clock source when the device is programmed using the oscillator selection or the FOSC<2:0> bits in the Configuration Word register (CONFIG).

In **INTOSC** mode, OSC1/CLKIN is available for general purpose I/O. OSC2/CLKOUT outputs the selected internal oscillator frequency divided by 4. The CLKOUT signal may be used to provide a clock for external circuitry, synchronization, calibration, test or other application requirements.

In **INTOSCIO** mode, OSC1/CLKIN and OSC2/CLKOUT are available for general purpose I/O.

3.5.2 HFINTOSC

The High-Frequency Internal Oscillator (HFINTOSC) is a factory calibrated 8 MHz internal clock source. The frequency of the HFINTOSC can be altered via software using the OSCTUNE register (Register 3-2).

The output of the HFINTOSC connects to a postscaler and multiplexer (see Figure 3-1). One of seven frequencies can be selected via software using the IRCF<2:0> bits of the OSCCON register. See **Section 3.5.4 "Frequency Select Bits (IRCF)"** for more information.

The HFINTOSC is enabled by selecting any frequency between 8 MHz and 125 kHz by setting the IRCF<2:0> bits of the OSCCON register ≠ 000. Then, set the System Clock Source (SCS) bit of the OSCCON register to '1' or enable Two-Speed Start-up by setting the IESO bit in the Configuration Word register (CONFIG) to '1'.

The HF Internal Oscillator (HTS) bit of the OSCCON register indicates whether the HFINTOSC is stable or not.

4.2 Additional Pin Functions

Every PORTA pin on the PIC16F684 has an interrupt-on-change option and a weak pull-up option. RA0 has an Ultra Low-Power Wake-up option. The next three sections describe these functions.

4.2.1 ANSEL REGISTER

The ANSEL register is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSEL bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSEL bits has no affect on digital output functions. A pin with TRIS clear and ANSEL set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

4.2.2 WEAK PULL-UPS

Each of the PORTA pins, except RA3, has an individually configurable internal weak pull-up. Control bits WPUAx enable or disable each pull-up. Refer to Register 4-4. Each weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset by the RAPU bit of the OPTION register). A weak pull-up is automatically enabled for RA3 when configured as MCLR and disabled when RA3 is an I/O. There is no software control of the MCLR pull-up.

4.2.3 INTERRUPT-ON-CHANGE

Each of the PORTA pins is individually configurable as an interrupt-on-change pin. Control bits IOCAx enable or disable the interrupt function for each pin. Refer to Register 4-5. The interrupt-on-change is disabled on a Power-on Reset.

For enabled interrupt-on-change pins, the values are compared with the old value latched on the last read of PORTA. The 'mismatch' outputs of the last read are OR'd together to set the PORTA Change Interrupt Flag bit (RAIF) in the INTCON register (Register 2-3).

This interrupt can wake the device from Sleep. The user, in the Interrupt Service Routine, clears the interrupt by:

a) Any read or write of PORTA. This will end the mismatch condition, then,

b) Clear the flag bit RAIF.

A mismatch condition will continue to set flag bit RAIF. Reading PORTA will end the mismatch condition and allow flag bit RAIF to be cleared. The latch holding the last read value is not affected by a MCLR nor Brown-out Reset. After these resets, the RAIF flag will continue to be set if a mismatch is present.

Note:	If a change on the I/O pin should occur when any PORTA operation is being executed, then the RAIF interrupt flag may not get set.

REGISTER 4-3: ANSEL: ANALOG SELECT REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **ANS<7:0>**: Analog Select bits

Analog select between analog or digital function on pins AN<7:0>, respectively.

1 = Analog input. Pin is assigned as analog input(1).

0 = Digital I/O. Pin is assigned to port or special function.

Note 1: Setting a pin to an analog input automatically disables the digital input circuitry, weak pull-ups and interrupt-on-change, if available. The corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

4.2.5 PIN DESCRIPTIONS AND DIAGRAMS

Each PORTA pin is multiplexed with other functions. The pins and their combined functions are briefly described here. For specific information about individual functions such as the Comparator or the ADC, refer to the appropriate section in this data sheet.

4.2.5.1 RA0/AN0/C1IN+/ICSPDAT/ULPWU

Figure 4-1 shows the diagram for this pin. The RA0 pin is configurable to function as one of the following:

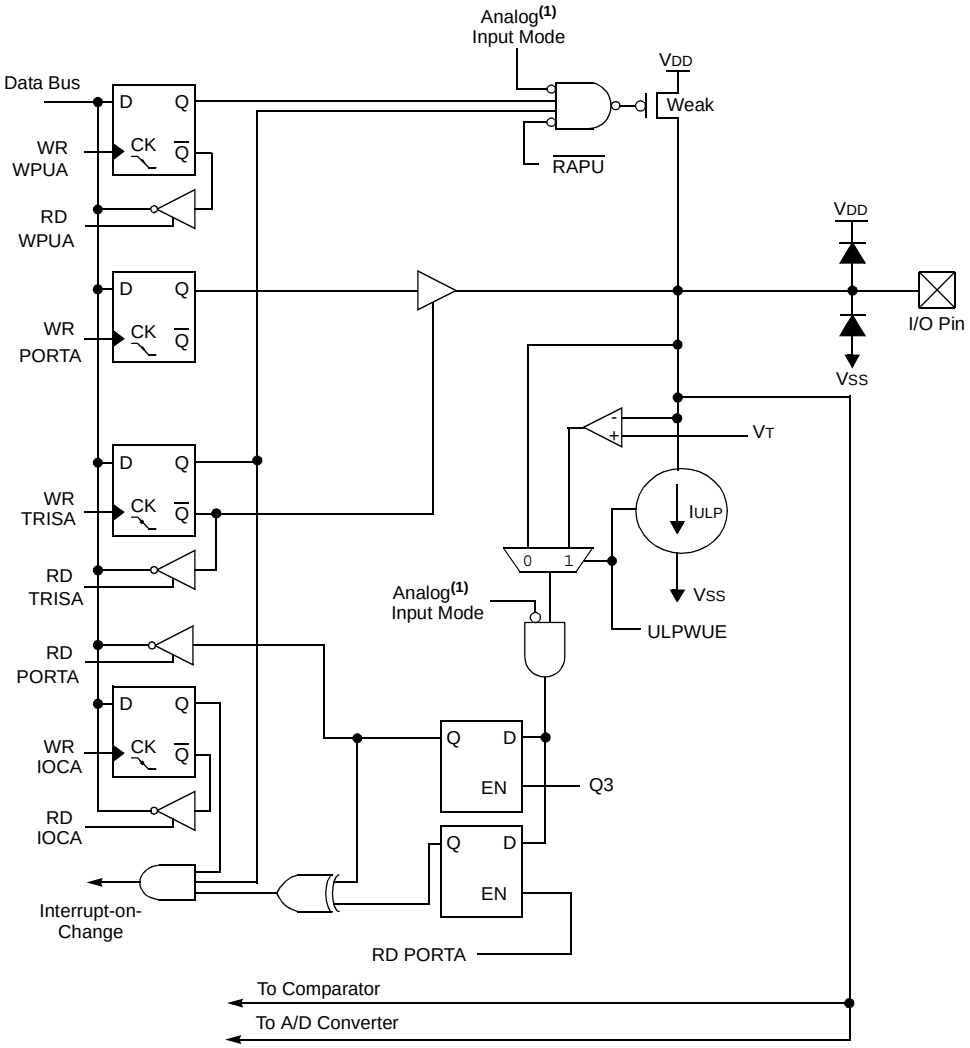
- a general purpose I/O
- an analog input for the ADC
- an analog non-inverting input to the comparator
- In-Circuit Serial Programming data
- an analog input for the Ultra Low-Power Wake-Up

4.2.5.2 RA1/AN1/C1IN-/VREF/ICSPCLK

Figure 4-2 shows the diagram for this pin. The RA1 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the ADC
- an analog inverting input to the comparator
- a voltage reference input for the ADC
- In-Circuit Serial Programming clock

FIGURE 4-1: BLOCK DIAGRAM OF RA0



Note 1: Comparator mode and ANSEL determines Analog Input mode.

5.1.3 SOFTWARE PROGRAMMABLE PRESCALER

A single software programmable prescaler is available for use with either Timer0 or the Watchdog Timer (WDT), but not both simultaneously. The prescaler assignment is controlled by the PSA bit of the OPTION register. To assign the prescaler to Timer0, the PSA bit must be cleared to a '0'.

There are 8 prescaler options for the Timer0 module ranging from 1:2 to 1:256. The prescale values are selectable via the PS<2:0> bits of the OPTION register. In order to have a 1:1 prescaler value for the Timer0 module, the prescaler must be assigned to the WDT module.

The prescaler is not readable or writable. When assigned to the Timer0 module, all instructions writing to the TMR0 register will clear the prescaler.

When the prescaler is assigned to WDT, a CLRWDT instruction will clear the prescaler along with the WDT.

5.1.3.1 Switching Prescaler Between Timer0 and WDT Modules

As a result of having the prescaler assigned to either Timer0 or the WDT, it is possible to generate an unintended device Reset when switching prescaler values. When changing the prescaler assignment from Timer0 to the WDT module, the instruction sequence shown in Example 5-1 must be executed.

EXAMPLE 5-1: CHANGING PRESCALER (TIMER0 → WDT)

```
BANKSEL  TMR0            ;
CLRWDT                   ;Clear WDT
CLRF     TMR0            ;Clear TMR0 and
                         ; prescaler
BANKSEL  OPTION_REG      ;
BSF      OPTION_REG,PSA  ;Select WDT
CLRWDT                   ;
                         ;
MOVLW    b'11111000'     ;Mask prescaler
ANDWF    OPTION_REG,W    ; bits
IORLW    b'00000101'     ;Set WDT prescaler
MOVWF    OPTION_REG      ; to 1:32
```

When changing the prescaler assignment from the WDT to the Timer0 module, the following instruction sequence must be executed (see Example 5-2).

EXAMPLE 5-2: CHANGING PRESCALER (WDT → TIMER0)

```
CLRWDT                   ;Clear WDT and
                         ;prescaler
BANKSEL OPTION_REG       ;
MOVLW   b'11110000'      ;Mask TMR0 select and
ANDWF   OPTION_REG,W     ; prescaler bits
IORLW   b'00000011'      ;Set prescale to 1:16
MOVWF   OPTION_REG       ;
```

5.1.4 TIMER0 INTERRUPT

Timer0 will generate an interrupt when the TMR0 register overflows from FFh to 00h. The T0IF interrupt flag bit of the INTCON register is set every time the TMR0 register overflows, regardless of whether or not the Timer0 interrupt is enabled. The T0IF bit must be cleared in software. The Timer0 interrupt enable is the T0IE bit of the INTCON register.

Note:	The Timer0 interrupt cannot wake the processor from Sleep since the timer is frozen during Sleep.

5.1.5 USING TIMER0 WITH AN EXTERNAL CLOCK

When Timer0 is in Counter mode, the synchronization of the T0CKI input and the Timer0 register is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks. Therefore, the high and low periods of the external clock source must meet the timing requirements as shown in **Section 15.0 "Electrical Specifications"**.

10.2 Reading the EEPROM Data Memory

To read a data memory location, the user must write the address to the EEADR register and then set control bit RD of the EECON1 register, as shown in Example 10-1. The data is available, at the very next cycle, in the EEDAT register. Therefore, it can be read in the next instruction. EEDAT holds this value until another read, or until it is written to by the user (during a write operation).

EXAMPLE 10-1: DATA EEPROM READ

```
    BANKSEL     EEADR       ;
    MOVLW       CONFIG_ADDR ;
    MOVWF       EEADR       ;Address to read
    BSF         EECON1,RD   ;EE Read
    MOVF        EEDAT,W     ;Move data to W
```

10.3 Writing to the EEPROM Data Memory

To write an EEPROM data location, the user must first write the address to the EEADR register and the data to the EEDAT register. Then the user must follow a specific sequence to initiate the write for each byte, as shown in Example 10-2.

EXAMPLE 10-2: DATA EEPROM WRITE

```
    BANKSEL  EECON1       ;
    BSF      EECON1,WREN  ;Enable write
    BCF      INTCON,GIE   ;Disable INTs
    BTFSC    INTCON,GIE   ;See AN576
    GOTO     $-2          ;
    MOVLW    55h          ;Unlock write
    MOVWF    EECON2       ;
    MOVLW    AAh          ;
    MOVWF    EECON2       ;
    BSF      EECON1,WR    ;Start the write
    BSF      INTCON,GIE   ;Enable INTS
```

Required Sequence

The write will not initiate if the above sequence is not exactly followed (write 55h to EECON2, write AAh to EECON2, then set WR bit) for each byte. We strongly recommend that interrupts be disabled during this code segment. A cycle count is executed during the required sequence. Any number that is not equal to the required cycles to execute the required sequence will prevent the data from being written into the EEPROM.

Additionally, the WREN bit in EECON1 must be set to enable write. This mechanism prevents accidental writes to data EEPROM due to errant (unexpected) code execution (i.e., lost programs). The user should keep the WREN bit clear at all times, except when updating EEPROM. The WREN bit is not cleared by hardware.

After a write sequence has been initiated, clearing the WREN bit will not affect this write cycle. The WR bit will be inhibited from being set unless the WREN bit is set.

At the completion of the write cycle, the WR bit is cleared in hardware and the EE Write Complete Interrupt Flag bit (EEIF) is set. The user can either enable this interrupt or poll this bit. The EEIF bit of the PIR1 register must be cleared by software.

10.4 Write Verify

Depending on the application, good programming practice may dictate that the value written to the data EEPROM should be verified (see Example 10-3) to the desired value to be written.

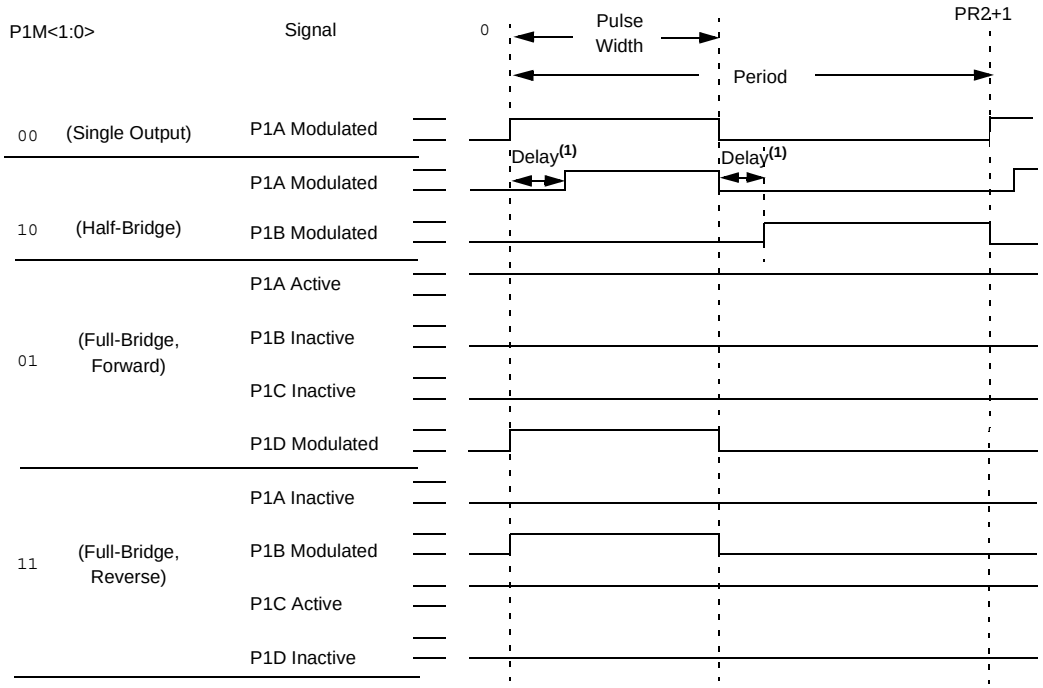
EXAMPLE 10-3: WRITE VERIFY

```
    BANKSELEEDAT        ;
    MOVF    EEDAT,W     ;EEDAT not changed
                        ;from previous write
    BSF     EECON1,RD   ;YES, Read the
                        ;value written
    XORWF   EEDAT,W
    BTFSS   STATUS,Z    ;Is data the same
    GOTO    WRITE_ERR   ;No, handle error
    :                   ;Yes, continue
```

10.4.1 USING THE DATA EEPROM

The data EEPROM is a high-endurance, byte addressable array that has been optimized for the storage of frequently changing information (e.g., program variables or other data that are updated often). When variables in one section change frequently, while variables in another section do not change, it is possible to exceed the total number of write cycles to the EEPROM (specification D124) without exceeding the total number of write cycles to a single byte (specifications D120 and D120A). If this is the case, then a refresh of the array must be performed. For this reason, variables that change infrequently (such as constants, IDs, calibration, etc.) should be stored in Flash program memory.

FIGURE 11-6: EXAMPLE PWM (ENHANCED MODE) OUTPUT RELATIONSHIPS (ACTIVE-HIGH STATE)



Relationships:

- Period = 4 * Tosc * (PR2 + 1) * (TMR2 Prescale Value)
- Pulse Width = Tosc * (CCPR1L<7:0>:CCP1CON<5:4>) * (TMR2 Prescale Value)
- Delay = 4 * Tosc * (PWM1CON<6:0>)

Note 1: Dead-band delay is programmed using the PWM1CON register (**Section 11.4.6 "Programmable Dead-Band Delay mode"**).

12.0 SPECIAL FEATURES OF THE CPU

The PIC16F684 has a host of features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving features and offer code protection.

These features are:

- Reset
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR)
- Interrupts
- Watchdog Timer (WDT)
- Oscillator selection
- Sleep
- Code protection
- ID Locations
- In-Circuit Serial Programming

The PIC16F684 has two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 64 ms (nominal) on power-up only, designed to keep the part in Reset while the power supply stabilizes. There is also circuitry to reset the device if a brown-out occurs, which can use the Power-up Timer to provide at least a 64 ms Reset. With these three functions-on-chip, most applications need no external Reset circuitry.

The Sleep mode is designed to offer a very low-current Power-Down mode. The user can wake-up from Sleep through:

- External Reset
- Watchdog Timer Wake-up
- An interrupt

Several oscillator options are also made available to allow the part to fit the application. The INTOSC option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options (see Register 12-1).

12.1 Configuration Bits

The Configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1') to select various device configurations as shown in Register 12-1. These bits are mapped in program memory location 2007h.

Note:	Address 2007h is beyond the user program memory space. It belongs to the special configuration memory space (2000h-3FFFh), which can be accessed only during programming. See "PIC12F6XX/16F6XX *Memory Programming Specification*" (DS41204) for more information.

12.5 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (e.g., W and STATUS registers). This must be implemented in software.

Temporary holding registers W_TEMP and STATUS_TEMP should be placed in the last 16 bytes of GPR (see Figure 2-2). These 16 locations are common to all banks and do not require banking. This makes context save and restore operations simpler. The code shown in Example 12-1 can be used to:

- Store the W register
- Store the STATUS register
- Execute the ISR code
- Restore the Status (and Bank Select Bit register)
- Restore the W register

Note: The PIC16F684 does not require saving the PCLATH. However, if computed GOTOs are used in both the ISR and the main code, the PCLATH must be saved and restored in the ISR.

EXAMPLE 12-1: SAVING STATUS AND W REGISTERS IN RAM

```
MOVWF   W_TEMP              ;Copy W to TEMP register
SWAPF   STATUS,W            ;Swap status to be saved into W
                            ;Swaps are used because they do not affect the status bits
MOVWF   STATUS_TEMP         ;Save status to bank zero STATUS_TEMP register
:
:(ISR)                      ;Insert user code here
:
SWAPF   STATUS_TEMP,W       ;Swap STATUS_TEMP register into W
                            ;(sets bank to original state)
MOVWF   STATUS              ;Move W into STATUS register
SWAPF   W_TEMP,F            ;Swap W_TEMP
SWAPF   W_TEMP,W            ;Swap W_TEMP into W
```

13.2 Instruction Descriptions

ADDLW	Add literal and W
Syntax:	[*label*] ADDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) + k → (W)
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the eight-bit literal 'k' and the result is placed in the W register.

ADDWF	Add W and f
Syntax:	[*label*] ADDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) + (f) → (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

ANDLW	AND literal with W
Syntax:	[*label*] ANDLW k
Operands:	0 ≤ k ≤ 255
Operation:	(W) .AND. (k) → (W)
Status Affected:	Z
Description:	The contents of W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.

ANDWF	AND W with f
Syntax:	[*label*] ANDWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) .AND. (f) → (destination)
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

BCF	Bit Clear f
Syntax:	[*label*] BCF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	0 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is cleared.

BSF	Bit Set f
Syntax:	[*label*] BSF f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	1 → (f<b>)
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

BTFSC	Bit Test, Skip if Clear
Syntax:	[*label*] BTFSC f,b
Operands:	0 ≤ f ≤ 127 0 ≤ b ≤ 7
Operation:	skip if (f<b>) = 0
Status Affected:	None
Description:	If bit 'b' in register 'f' is '1', the next instruction is executed. If bit 'b', in register 'f', is '0', the next instruction is discarded, and a NOP is executed instead, making this a 2-cycle instruction.

14.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C18 and MPLAB C30 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB ASM30 Assembler/Linker/Library
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD 2
- Device Programmers
  - PICSTART® Plus Development Programmer
  - MPLAB PM3 Device Programmer
  - PICkit™ 2 Development Programmer
- Low-Cost Demonstration and Development Boards and Evaluation Kits

14.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
  - Simulator
  - Programmer (sold separately)
  - Emulator (sold separately)
  - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Visual device initializer for easy register initialization
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as HI-TECH Software C Compilers and IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either assembly or C)
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
  - Source files (assembly or C)
  - Mixed assembly and C
  - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

15.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40° to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +6.5V
Voltage on $\overline{MCLR}$ with respect to Vss ..... -0.3V to +13.5V
Voltage on all other pins with respect to V_{SS} ..... -0.3V to (V_{DD} + 0.3V)
Total power dissipation(1) ..... 800 mW
Maximum current out of V_{SS} pin ..... 95 mA
Maximum current into V_{DD} pin ..... 95 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ± 20 mA
Output clamp current, I_{OK} (Vo < 0 or Vo > V_{DD}) ..... ± 20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by PORTA and PORTC (combined) ..... 90 mA
Maximum current sourced PORTA and PORTC (combined) ..... 90 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (Vol \times I_{OL})$.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

15.2 DC Characteristics: PIC16F684-I (Industrial) PIC16F684-E (Extended)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min	Typ†	Max	Units	Conditions	
						VDD	Note
D010	**Supply Current (IDD)(1, 2)**	—	11	16	µA	2.0	FOSC = 32 kHz LP Oscillator mode
		—	18	28	µA	3.0	
		—	35	54	µA	5.0	
D011*		—	140	240	µA	2.0	FOSC = 1 MHz XT Oscillator mode
		—	220	380	µA	3.0	
		—	380	550	µA	5.0	
D012		—	260	360	µA	2.0	FOSC = 4 MHz XT Oscillator mode
		—	420	650	µA	3.0	
		—	0.8	1.1	mA	5.0	
D013*		—	130	220	µA	2.0	FOSC = 1 MHz EC Oscillator mode
		—	215	360	µA	3.0	
		—	360	520	µA	5.0	
D014		—	220	340	µA	2.0	FOSC = 4 MHz EC Oscillator mode
		—	375	550	µA	3.0	
		—	0.65	1.0	mA	5.0	
D015		—	8	20	µA	2.0	FOSC = 31 kHz LFINTOSC mode
		—	16	40	µA	3.0	
		—	31	65	µA	5.0	
D016*		—	340	450	µA	2.0	FOSC = 4 MHz HFINTOSC mode
		—	500	700	µA	3.0	
		—	0.8	1.2	mA	5.0	
D017		—	410	650	µA	2.0	FOSC = 8 MHz HFINTOSC mode
		—	700	950	µA	3.0	
		—	1.30	1.65	mA	5.0	
D018		—	230	400	µA	2.0	FOSC = 4 MHz EXTRC mode(3)
		—	400	680	µA	3.0	
		—	0.63	1.1	mA	5.0	
D019		—	2.6	3.25	mA	4.5	FOSC = 20 MHz HS Oscillator mode
		—	2.8	3.35	mA	5.0	

* These parameters are characterized but not tested.

† Data in 'Typ' column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{MCLR}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ.

15.5 DC Characteristics: PIC16F684-I (Industrial) PIC16F684-E (Extended) (Continued)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D100	IULP	Ultra Low-Power Wake-Up Current	—	200	—	nA	See Application Note AN879, "*Using the Microchip Ultra Low-Power Wake-up Module*" (DS00879)
		Capacitive Loading Specs on Output Pins					
D101*	COSC2	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101A*	CIO	All I/O pins	—	—	50	pF	
		Data EEPROM Memory					
D120	ED	Byte Endurance	100K	1M	—	E/W	-40°C ≤ TA ≤ +85°C
D120A	ED	Byte Endurance	10K	100K	—	E/W	+85°C ≤ TA ≤ +125°C
D121	VDRW	VDD for Read/Write	VMIN	—	5.5	V	Using EECON1 to read/write VMIN = Minimum operating voltage
D122	TDEW	Erase/Write Cycle Time	—	5	6	ms	
D123	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated
D124	TREF	Number of Total Erase/Write Cycles before Refresh(4)	1M	10M	—	E/W	-40°C ≤ TA ≤ +85°C
		Program Flash Memory					
D130	EP	Cell Endurance	10K	100K	—	E/W	-40°C ≤ TA ≤ +85°C
D130A	ED	Cell Endurance	1K	10K	—	E/W	+85°C ≤ TA ≤ +125°C
D131	VPR	VDD for Read	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D132	VPEW	VDD for Erase/Write	4.5	—	5.5	V	
D133	TPEW	Erase/Write cycle time	—	2	2.5	ms	
D134	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated

* These parameters are characterized but not tested.

† Data in 'Typ' column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in RC mode.

2: Negative current is defined as current sourced by the pin.

3: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

4: See **Section 10.4.1 "Using the Data EEPROM"** for additional information.

5: Including OSC2 in CLKOUT mode.

15.8 AC Characteristics: PIC16F684 (Industrial, Extended)

FIGURE 15-4: CLOCK TIMING

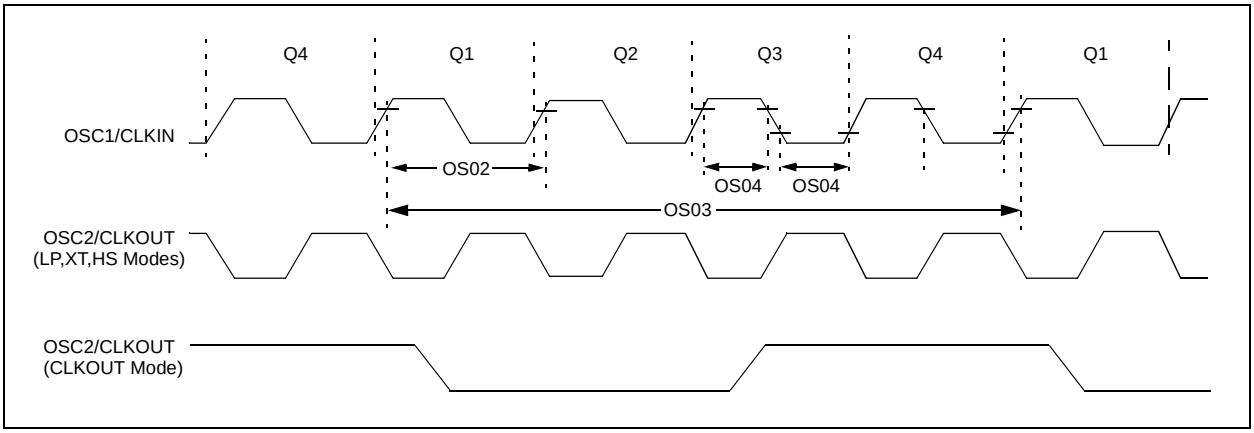


TABLE 15-1: CLOCK OSCILLATOR TIMING REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)
Operating temperature -40°C ≤ TA ≤ +125°C

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
OS01	FOSC	External CLKIN Frequency(1)	DC	—	37	kHz	LP Oscillator mode
			DC	—	4	MHz	XT Oscillator mode
			DC	—	20	MHz	HS Oscillator mode
			DC	—	20	MHz	EC Oscillator mode
		Oscillator Frequency(1)	—	32.768	—	kHz	LP Oscillator mode
			0.1	—	4	MHz	XT Oscillator mode
			1	—	20	MHz	HS Oscillator mode
			DC	—	4	MHz	RC Oscillator mode
OS02	TOSC	External CLKIN Period(1)	27	—	•	µs	LP Oscillator mode
			250	—	•	ns	XT Oscillator mode
			50	—	•	ns	HS Oscillator mode
			50	—	•	ns	EC Oscillator mode
		Oscillator Period(1)	—	30.5	—	µs	LP Oscillator mode
			250	—	10,000	ns	XT Oscillator mode
			50	—	1,000	ns	HS Oscillator mode
			250	—	—	ns	RC Oscillator mode
OS03	TCY	Instruction Cycle Time(1)	200	TCY	DC	ns	TCY = 4/FOSC
OS04*	TosH, TosL	External CLKIN High, External CLKIN Low	2	—	—	µs	LP oscillator
			100	—	—	ns	XT oscillator
			20	—	—	ns	HS oscillator
OS05*	TosR, TosF	External CLKIN Rise, External CLKIN Fall	0	—	•	ns	LP oscillator
			0	—	•	ns	XT oscillator
			0	—	•	ns	HS oscillator

* These parameters are characterized but not tested.

† Data in 'Typ' column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at 'min' values with an external clock applied to OSC1 pin. When an external clock input is used, the 'max' cycle time limit is 'DC' (no clock) for all devices.

FIGURE 15-5: CLKOUT AND I/O TIMING

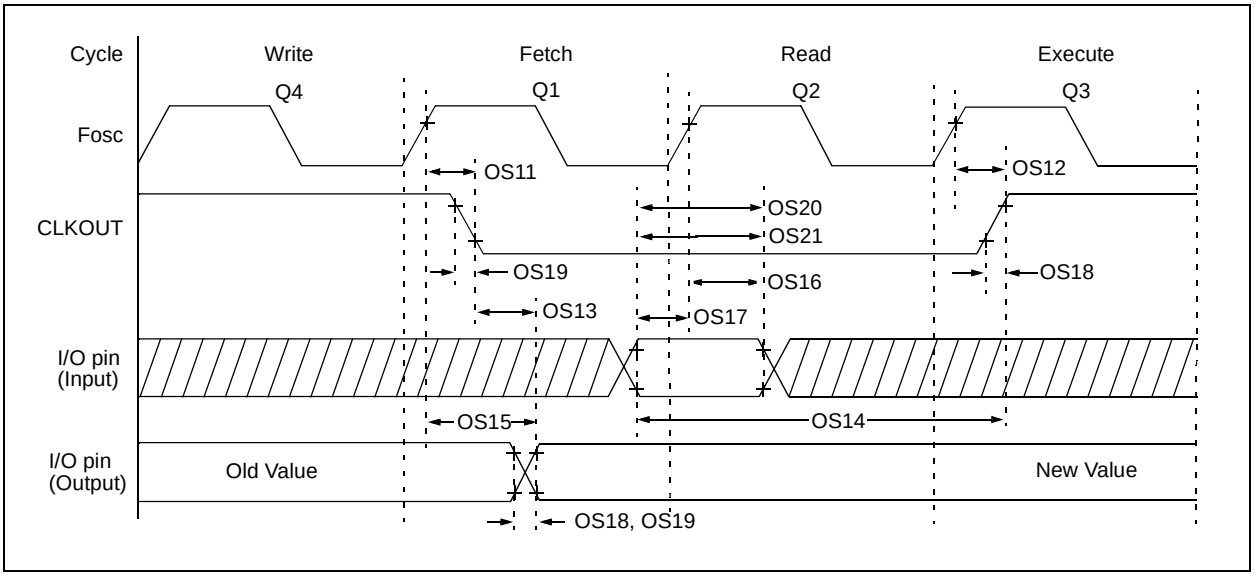


TABLE 15-3: CLKOUT AND I/O TIMING PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
OS11	TosH2ckL	FOSC↑ to CLKOUT↓ **(1)**	—	—	70	ns	VDD = 5.0V
OS12	TosH2ckH	FOSC↑ to CLKOUT↑ **(1)**	—	—	72	ns	VDD = 5.0V
OS13	TckL2ioV	CLKOUT↓ to Port out valid**(1)**	—	—	20	ns	
OS14	TioV2ckH	Port input valid before CLKOUT↑**(1)**	TOSC + 200 ns	—	—	ns	
OS15	TosH2ioV	FOSC↑ (Q1 cycle) to Port out valid	—	50	70*	ns	VDD = 5.0V
OS16	TosH2ioI	FOSC↑ (Q2 cycle) to Port input invalid (I/O in hold time)	50	—	—	ns	VDD = 5.0V
OS17	TioV2osH	Port input valid to FOSC↑ (Q2 cycle) (I/O in setup time)	20	—	—	ns	
OS18	TioR	Port output rise time**(2)**	— —	15 40	72 32	ns	VDD = 2.0V VDD = 5.0V
OS19	TioF	Port output fall time**(2)**	— —	28 15	55 30	ns	VDD = 2.0V VDD = 5.0V
OS20*	Tinp	INT pin input high or low time	25	—	—	ns	
OS21*	Trap	PORTA interrupt-on-change new input level time	TCY	—	—	ns	

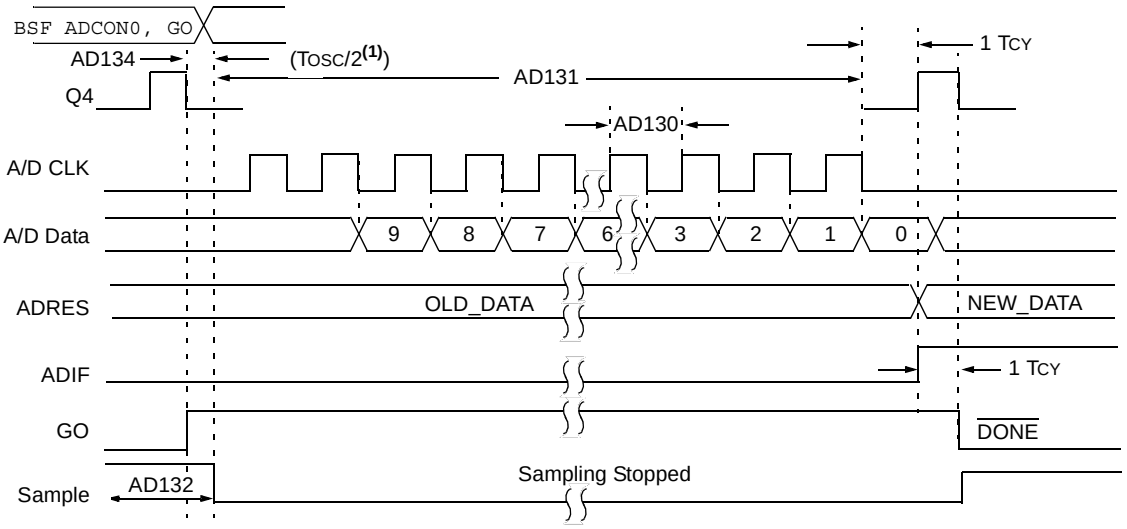
* These parameters are characterized but not tested.

† Data in 'Typ' column is at 5.0V, 25°C unless otherwise stated.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.

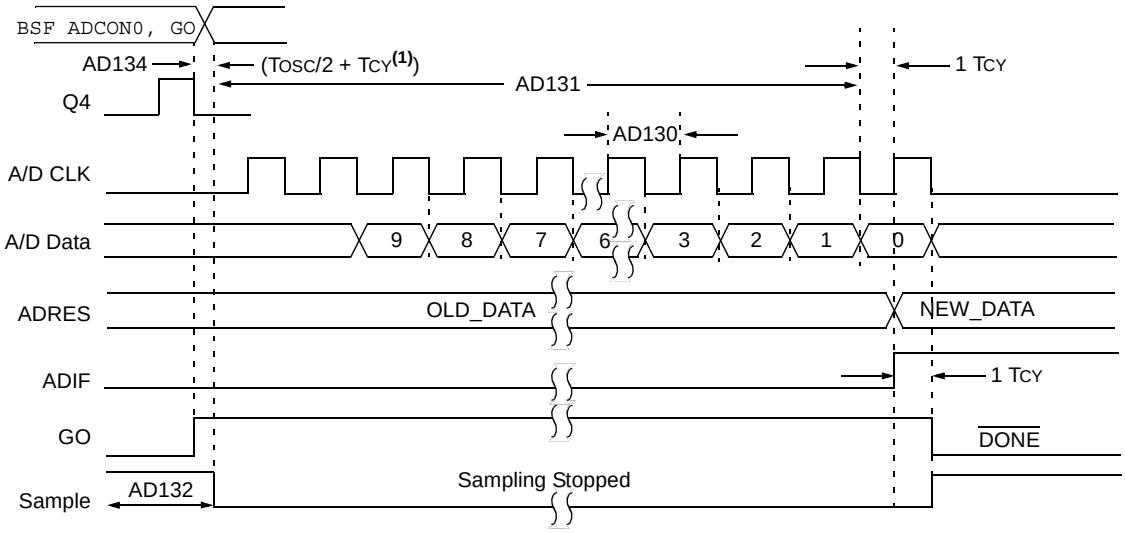
2: Includes OSC2 in CLKOUT mode.

FIGURE 15-10: PIC16F684 A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

FIGURE 15-11: PIC16F684 A/D CONVERSION TIMING (SLEEP MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

FIGURE 16-20: WDT PERIOD vs. TEMPERATURE OVER VDD (5.0V)

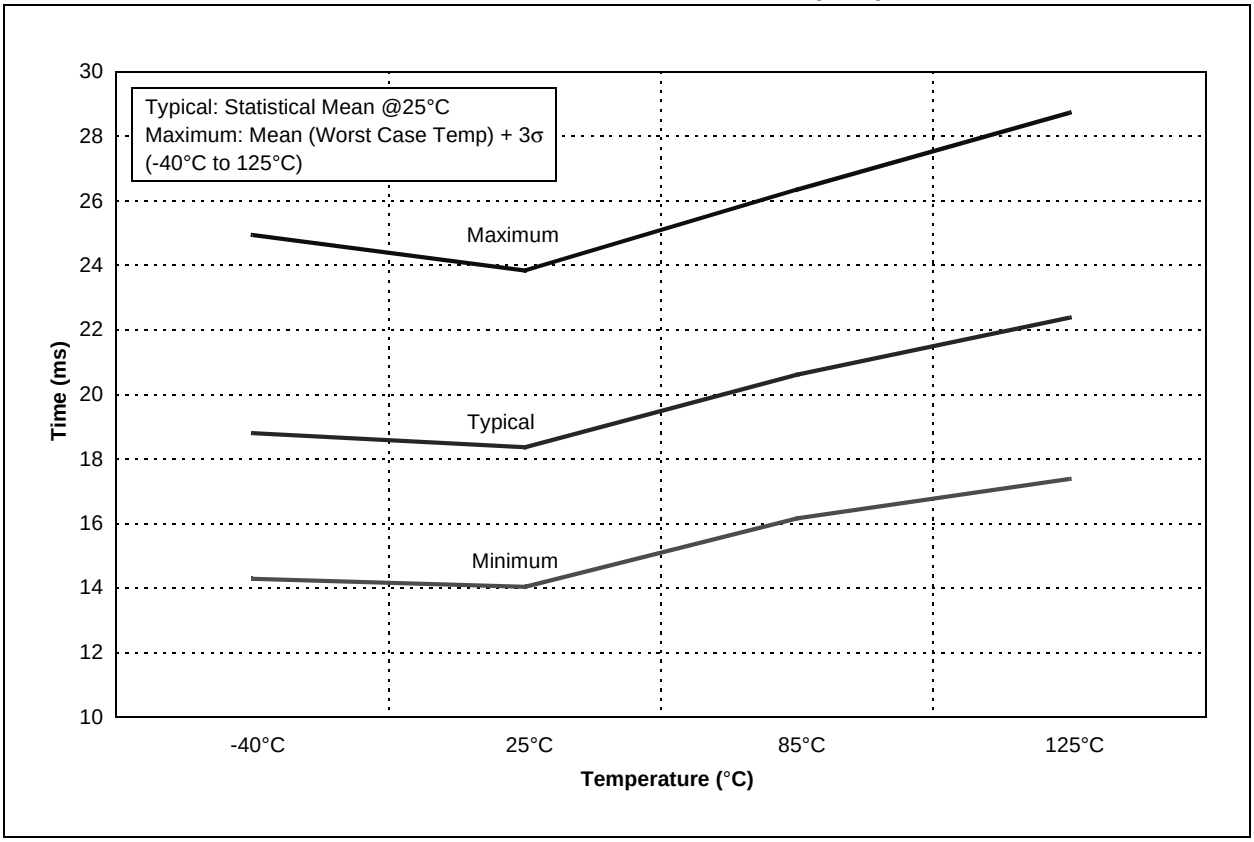


FIGURE 16-21: CVREF IPD vs. VDD OVER TEMPERATURE (HIGH RANGE)

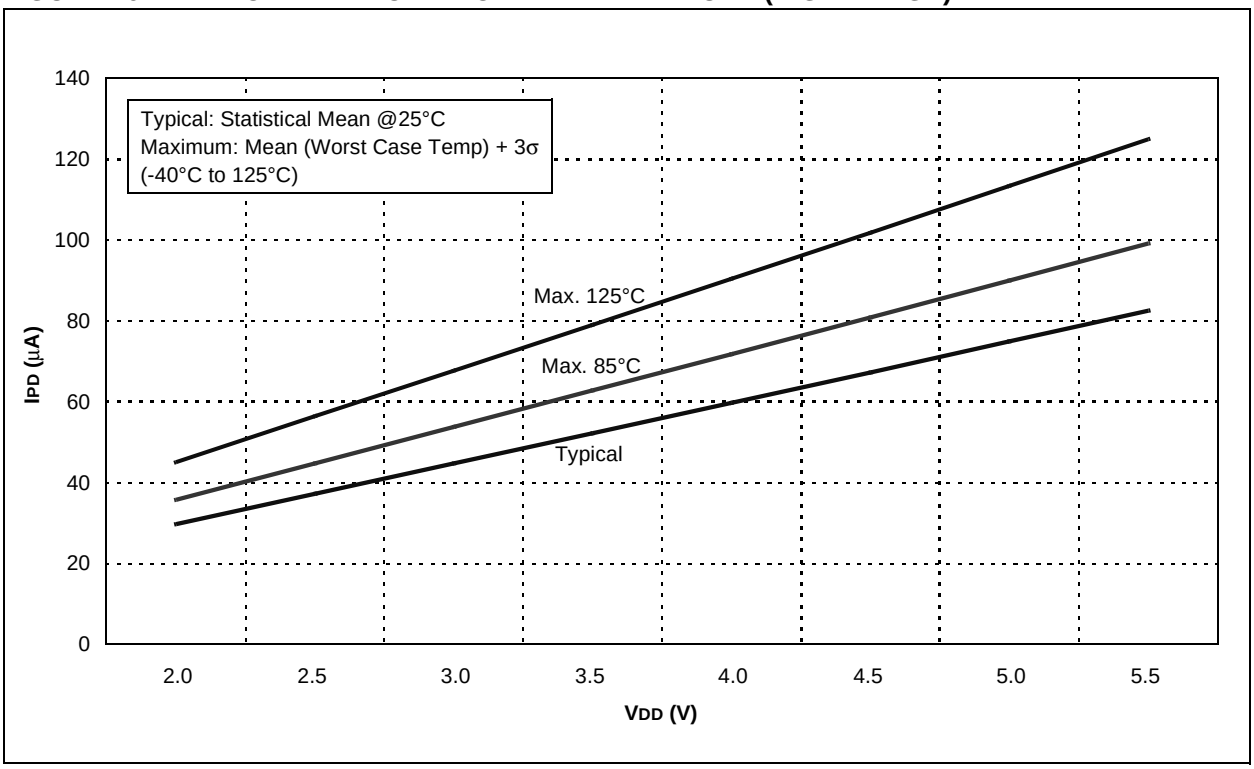


FIGURE 16-40: TYPICAL HFINTOSC FREQUENCY CHANGE vs. VDD (-40°C)